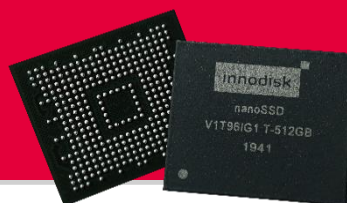


Datasheet

nanoSSD

PCIe 3TE7 series

- PCIe Gen. III x2, NVMe 1.3
- Excellent data transfer speed
- LDPC ECC engine supported.
- End-to-end Data Path Protection
- Small BGA package form factor
- Support Wide Temperature



Introduction

Innodisk nanoSSD PCIe 3TE7 is an NVM Express storage device designed as the standard 11.5*13.0 mm² ball grid array (BGA) package form factor with PCIe interface. The nanoSSD supports PCIe Gen III x2 within a tiny dimension, and it is compliant with NVM 1.3 providing excellent performance. Moreover, it adopts industrial 3D TLC NAND Flash providing high endurance and reliability, as well as low power consumption and high reliability. It offers an ideal solution for embedded, automotive, medical, gaming and most industrial applications.

nanoSSD PCIe 3TE7 series

Contact us for more information
about the nanoSSD PCIe 3TE7

Innodisk is a service-driven provider of industrial embedded flash and DRAM storage products and technologies, with a focus on the cloud computing, industrial/embedded, and aerospace and defense industries.

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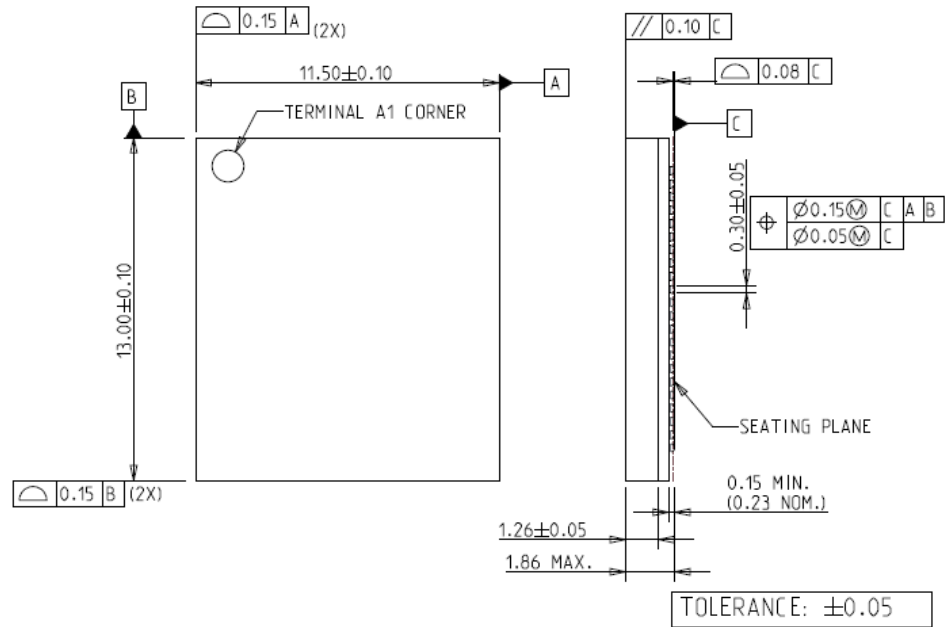
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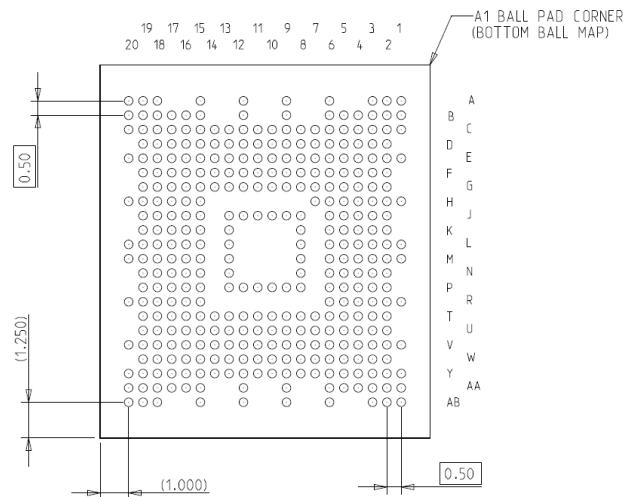
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Drawing



Bottom View (345-ball)



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Specifications

Interface	PCIe Gen. III x2
Flash Type	3D TLC
Capacity	32GB~512GB
Max. Channels	4
Sequential R/W (MB/sec, max.)	1650/1350
Max. Power Consumption	1.8 W
Thermal Sensor	√
External DRAM Buffer	-
H/W Write Protect	-
ATA Security	√
S.M.A.R.T.	√
Dimension (WxLxH)	11.5 X 13.0 X 1.86 mm (*see detailed in the above mechanical drawings)
Environment	Vibration: 20G @7~2000Hz Shock: 1500G @ 0.5ms Storage Temperature: -40°C ~ +85°C MTBF: 3,000,000 hour

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Ordering Information

Operation Temp.	32GB	64GB	128GB	256GB	512GB
Standard Grade (0°C ~ +70°C)	DENSD-32GIG1ECASH	DENSD-64GIG1ECADH	DENSD-A28IG1ECAQH	DENSD-B56IG1ECAQH	DENSD-C12IG1ECAQH
Industrial Grade (-40°C ~ +85°C)	DENSD-32GIG1EWASH	DENSD-64GIG1EWADH	DENSD-A28IG1EWAQH	DENSD-B56IG1EWAQH	DENSD-C12IG1EWAQH

